ABSOLUTE MAXIMUM RATINGS

V _{cc}	+7V
Input Voltages:	
Logic	0.3V to (V _{cc} +0.5V)
	0.3V to (V _{CC} +0.5V)
Receivers	±15.5Ý
Output Voltages:	
Logic	0.3V to (V _{cc} +0.5V)
	±12Ý
	0.3V to (V _{cc} +0.5V)
Storage Temperature	65°C to +150°C
Power Dissipation	1520mW
(derate 19.0mW/°C above +70°C)	
Junction Temperature T,	+141°C

Package Derat	ting:	
Ø ,	36.9	°C/W
	6.5	

These are stress ratings only and functional operation of the device at these ratings or any other above those indicated in the operation sections of the specifications below is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability.

STORAGE CONSIDERATIONS

Due to the relatively large package size of the 100-pin quad flat-pack, storage in a low humidity environment is preferred. Large high density plastic packages are moisture sensitive and should be stored in Dry Vapor Barrier Bags. Prior to usage, the parts should remain bagged and stored below 40°C and 60%RH. If the parts are removed from the bag, they should be

used within 48 hours or stored in an environment at or below 20%RH. If the above conditions cannot be followed, the parts should be baked for four hours at 125°C in order to remove moisture prior to soldering. Exar ships the 100-pin LQFP in Dry Vapor Barrier Bags with a humidity indicator card and desiccant pack. The humidity indicator should be below 30%RH.

ELECTRICAL SPECIFICATIONS

 $T_A = 0$ to 70°C and $V_{CC} = 3.3V \pm 5\%$ unless otherwise noted. The \blacklozenge denotes the specifications which apply over the full operating temperature range (-40°C to +85°C), unless otherwise specified.

PARAMETER	MIN.	TYP.	MAX.		UNITS	CONDITIONS	
LOGIC INPUTS							
V _{IL}			0.8	*	V		
V _{IH}	2.0			*	V		
LOGIC OUTPUTS							
V _{OL}			0.4	•	V	I _{OUT} = -3.2mA	
V _{OH}	V _{cc} - 0.6	V _{cc} - 0.3		*	V	I _{OUT} = 1.0mA	
V.28 DRIVER DC Parameter	s (OUTPU	TS)	•				
Open Circuit Voltage			+/-10	*	V	Per Figure 1	
Loaded Voltage	+/-5.0			•	V	Per Figure 2	
Short-Circuit Current			+/-100	*	mA	Per Figure 4	
Power-Off Impedance	300			*	Ω	Per Figure 5	
V.28 DRIVER AC Parameter	s (Output	s)				V _{CC} = 3.3V for AC parameters	
Transition Time			1.5	+	μs	Per Figure 6, +3V to -3V	
Instantaneous Slew Rate			30		V/ µs	Per Figure 3	
Propagation Delay: t _{PHL}	0.5	1.0	3.0	٠	μs		
Propagation Delay: t _{PLH}	0.5	1.0	3.0	*	μs		
Max. Transmission Rate	120	230		•	kbps		

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 $T_A = 0$ to 70°C and $V_{CC} = 3.3V \pm 5\%$ unless otherwise noted. The \blacklozenge denotes the specifications which apply over the full operating temperature range (-40°C to +85°C), unless otherwise specified.

PARAMETER	MIN.	TYP.	MAX.		UNITS	CONDITIONS
V.28 RECEIVER DC Parame		•				
Input Impedance	3		7	*	kΩ	Per Figure 7
Open-Circuit Bias			+2.0	*	V	Per Figure 8
HIGH Threshold		1.7	3.0	*	V	
LOW Threshold	0.8	1.2		*	V	
V.28 RECEIVER AC Parame	ters					V _{cc} = 3.3V for AC parameters
Propagation Delay: t _{PHL}		100	500		ns	
Propagation Delay: t _{PLH}		100	500		ns	
Max. Transmission Rate	120	230			kbps	
V.10 DRIVER DC Parameters	s (Output	s)				
Open Circuit Voltage	+/-4.0		+/-6.0	*	V	Per Figure 9
Test-Terminated Voltage	0.9V _{cc}				V	Per Figure 10
Short-Circuit Current			+/-150		mA	Per Figure 11
Power-Off Current			+/-100	*	μΑ	Per Figure 12
V.10 DRIVER AC Parameters	s (Output	s)				V _{cc} = 3.3V for AC parameters
Transition Time			200	*	ns	Per Figure 13, 10% to 90%
Propagation Delay: t _{PHL}		100	500	*	ns	
Propagation Delay: t _{PLH}		100	500	*	ns	
Max. Transmission Rate	120			*	kbps	
V.10 RECEIVER DC Parame	ters (Inpu	ts)				•
Input Current	-3.25		+3.25		mA	Per Figures 14 and 15
Input Impedance	4			*	kΩ	
Sensitivity			+/-0.3	*	V	
V.10 RECEIVER AC Parame	ters					V _{cc} = 3.3V for AC parameters
Propagation Delay: t _{PHL}		120	250	+	ns	
Propagation Delay: t _{PLH}		120	250	*	ns	
Max. Transmission Rate	120			+	kbps	

 $T_A = 0$ to 70°C and $V_{CC} = 3.3V \pm 5\%$ unless otherwise noted. The \blacklozenge denotes the specifications which apply over the full operating temperature range (-40°C to +85°C), unless otherwise specified.

PARAMETER	MIN.	TYP.	MAX.		UNITS	CONDITIONS
V.11 DRIVER DC Parameter						
Open Circuit Voltage (V _{oc})			+/-6.0	*	V	Per Figure 16
Test Terminated Voltage	+/-2.0			*	V	Per Figure 17
	0.5(V _{oc})			*	V	
Balance			+/-0.4		V	Per Figure 17
Offset			+3.0	*	V	Per Figure 17
Short-Circuit Current			+/-150	*	mA	Per Figure 18
Power-Off Current			+/-100	*	μA	Per Figure 19
V.11 DRIVER AC Parameter	s (Output	s)				V _{cc} = 3.3V for AC parameters
Transition Time			10	*	ns	Per Figures 21 and 35, 10% to 90% using C _L = 50pF
Propagation Delay: t _{PHL}		30	85	*	ns	Per Figures 32 and 35
Propagation Delay: t _{PLH}		30	85	*	ns	Per Figures 32 and 35
Differential Skew		5	10	*	ns	Per Figures 32 and 35
Max. Transmission Rate	20			*	Mbps	
V.11 RECEIVER DC Parame	ters (Inpu	ts)			,	
Common Mode Range	-7		+7	*	V	
Sensitivity			+/-0.2	*	V	
Input Current	-3.25		+3.25		mA	Per Figures 20 and 22; Power on or off
Current with 100Ω Termination			+/-60		mA	Per Figures 23 and 24
Input Impedance	4			*	kΩ	
V.11 RECEIVER AC Parame	V _{cc} = 3.3V for AC parameters using CL = 50pF					
Propagation Delay: t _{PHL}		30	85		ns	Per Figures 32 and 37
Propagation Delay: t _{PLH}		30	85		ns	Per Figures 32 and 37
Skew		5	10		ns	Per Figure 32
Max. Transmission Rate	20				Mbps	

 $T_A = 0$ to 70°C and $V_{CC} = 3.3V \pm 5\%$ unless otherwise noted. The \bullet denotes the specifications which apply over the full operating temperature range (-40°C to +85°C), unless otherwise specified.

PARAMETER	MIN.	TYP.	MAX.		UNITS	CONDITIONS		
V.35 DRIVER DC Parameter	V.35 DRIVER DC Parameters (Outputs)							
Open Circuit Voltage			+/-1.20		V	Per Figure 16		
Test Terminated Voltage	+/-0.44		+/-0.66		٧	Per Figure 25		
Offset			+/-0.6	*	V	Per Figure 25		
Output Overshoot	-0.2V _{ST}		+0.2V _{ST}	*	V	Per Figure 25; V _{ST} = Steady State value		
Source Impedance	50		150	*	Ω	Per Figure 26; $Z_{S} = V_{2}/V_{1} \times 50$		
Short-Circuit Impedance	135		165		Ω	Per Figure 27		
V.35 DRIVER AC Parameter	s (Output	s)				V _{cc} = 3.3V for AC parameters		
Transition Time			20	•	ns			
Propagation Delay: t _{PHL}		30	85	•	ns	Per Figures 32 and 35; C _L = 20pF		
Propagation Delay: t _{PLH}		30	85	*	ns	Per Figures 32 and 35; C _L = 20pF		
Differential Skew			5	•	ns	Per Figures 32 and 35; C _L = 20pF		
Max. Transmission Rate	20			•	Mbps			
V.35 RECEIVER DC Parame	ters (Inpu	ts)	,					
Sensitivity		+/-50	+/-200	•	mV			
Source Impedance	90		110		Ω	Per Figure 29; $Z_s = V_2/V_1 \times 50\Omega$		
Short-Circuit Impedance	135		165		Ω	Per Figure 30		
V.35 RECEIVER AC Parame	ters					V _{CC} = 3.3V for AC parameters		
Propagation Delay: t _{PHL}		30	85		ns	Per Figures 32 and 37; C _L = 20pF		
Propagation Delay: t _{PLH}		30	85		ns	Per Figures 32 and 37; C _L = 20pF		
Skew		5	10		ns	Per Figure 32; C _L = 20pF		
Max. Transmission Rate	20				Mbps			
TRANSCEIVER LEAKAGE	CURRENT	S						
Driver Output 3-State Current			200		μA	Per Figure 31; Drivers Disabled		
Receiver Output 3-State Current		1	10		μA	D _x = 111		

 $T_A = 0$ to 70°C and $V_{CC} = 3.3V \pm 5\%$ unless otherwise noted. The \blacklozenge denotes the specifications which apply over the full operating temperature range (-40°C to +85°C), unless otherwise specified.

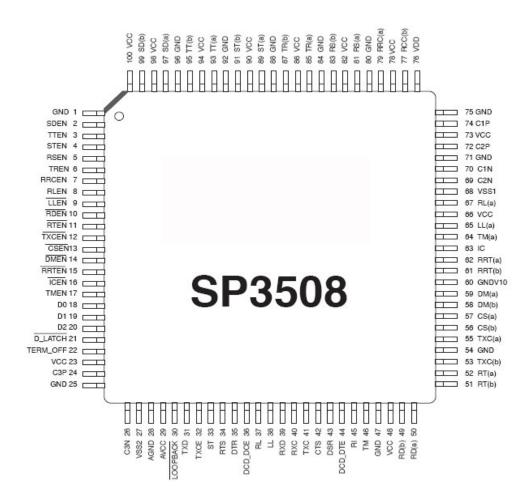
PARAMETER	MIN.	TYP.	MAX.		UNITS	CONDITIONS	
POWER REQUIREMENTS							
V _{cc}	3.15	3.3	3.45		V		
I _{cc} (No Mode Selected)		1		+	μA	All I_{cc} values are with V_{cc} = +3.3V	
(V.28 / RS-232)		95		*	mA	f _{IN} = 230kbps; Drivers active and loaded	
(V.11 / RS-422)		230		*	mA	f _{IN} = 20Mbps; Drivers active and loaded	
(EIA-530 & RS-449)		270		*	mA	f _{IN} = 20Mbps; Drivers active and loaded	
(V.35)		170		*	mA	V.35 @ f_{IN} = 20Mbps, V.28 @ f_{IN} = 230kbps	

 $\rm T_A$ = 0 to 70°C and $\rm V_{CC}$ = 3.3V \pm 5% unless otherwise noted.

PARAMETER	MIN.	TYP.	MAX.	Units	CONDITIONS
DRIVER DELAY TIME BETWEE	EN ACTIV	E MODE	AND TR	I-STATE	MODE
RS-232/V.28					
t _{PZL} ; Tri-state to Output LOW		0.70	5.0	μs	C _L = 100pF, Fig. 33 & 39 ; S ₁ closed
t _{PZH} ; Tri-state to Output HIGH		0.40	2.0	μs	C _L = 100pF, Fig. 33 & 39 ; S ₂ closed
t _{PLZ} ; Output LOW to Tri-state		0.20	2.0	μs	C _L = 100pF, Fig. 33 & 39 ; S ₁ closed
t _{PHZ} ; Output HIGH to Tri-state		0.40	2.0	μs	C _L = 100pF, Fig. 33 & 39 ; S ₂ closed
RS-423/V.10					
t _{PZL} ; Tri-state to Output LOW		0.15	2.0	μs	C _L = 100pF, Fig. 33 & 39 ; S ₁ closed
t _{PZH} ; Tri-state to Output HIGH		0.20	2.0	μs	C _L = 100pF, Fig. 33 & 39 ; S ₂ closed
t _{PLZ} ; Output LOW to Tri-state		0.20	2.0	μs	C _L = 100pF, Fig. 33 & 39 ; S ₁ closed
t _{PHZ} ; Output HIGH to Tri-state		0.15	2.0	μs	C _L = 100pF, Fig. 33 & 39 ; S ₂ closed
RS-422/V.11					
t _{PZL} ; Tri-state to Output LOW		2.80	10.0	μs	C _L = 100pF, Fig. 33 & 36 ; S ₁ closed
t _{PZH} ; Tri-state to Output HIGH		0.10	2.0	μs	C _L = 100pF, Fig. 33 & 36 ; S ₂ closed
t _{PLZ} ; Output LOW to Tri-state		0.10	2.0	μs	C _L = 15pF, Fig. 33 & 36 ; S ₁ closed
t _{PHZ} ; Output HIGH to Tri-state		0.10	2.0	μs	C _L = 15pF, Fig. 33 & 36 ; S ₂ closed
V.35					
t _{PZL} ; Tri-state to Output LOW		2.60	10.0	μs	C _L = 100pF, Fig. 33 & 36 ; S ₁ closed
t _{PZH} ; Tri-state to Output HIGH		0.10	2.0	μs	C _L = 100pF, Fig. 33 & 36 ; S ₂ closed
t _{PLZ} ; Output LOW to Tri-state		0.10	2.0	μs	C _L = 15pF, Fig. 33 & 36 ; S ₁ closed
t _{PHZ} ; Output HIGH to Tri-state		0.15	2.0	μs	C _L = 15pF, Fig. 33 & 36 ; S ₂ closed
RECEIVER DELAY TIME BETV	VEEN AC	TIVE MC	DE AND	TRI-STA	TE MODE
RS-232/V.28					
t _{PZL} ; Tri-state to Output LOW		0.12	2.0	μs	C _L = 100pF, Fig. 34 & 37 ; S ₁ closed
t _{PZH} ; Tri-state to Output HIGH		0.10	2.0	μs	C _L = 100pF, Fig. 34 & 37 ; S ₂ closed
t _{PLZ} ; Output LOW to Tri-state		0.10	2.0	μs	C _L = 100pF, Fig. 34 & 37 ; S ₁ closed
t _{PHZ} ; Output HIGH to Tri-state		0.10	2.0	μs	C _L = 100pF, Fig. 34 & 37 ; S ₂ closed
RS-423/V.10					
t _{PZL} ; Tri-state to Output LOW		0.10	2.0	μs	C _L = 100pF, Fig. 34 & 37 ; S ₁ closed
t _{PZH} ; Tri-state to Output HIGH		0.10	2.0	μs	C _L = 100pF, Fig. 34 & 37 ; S ₂ closed
t _{PLZ} ; Output LOW to Tri-state		0.10	2.0	μs	C _L = 100pF, Fig. 34 & 37 ; S ₁ closed
t _{PHZ} ; Output HIGH to Tri-state		0.10	2.0	μs	C _L = 100pF, Fig. 34 & 37 ; S ₂ closed

 $T_A = 0$ to 70°C and $V_{CC} = +3.3V$ unless otherwise noted.

PARAMETER	MIN.	TYP.	MAX.	UNITS	CONDITIONS
RS-422/V.11					
t _{PZL} ; Tri-state to Output LOW		0.10	2.0	μs	C _L = 100pF, Fig. 34 & 38 ; S ₁ closed
t _{PZH} ; Tri-state to Output HIGH		0.10	2.0	μs	C _L = 100pF, Fig. 34 & 38 ; S ₂ closed
t_{PLZ} ; Output LOW to Tri-state		0.10	2.0	μs	C ₁ = 15pF, Fig. 34 & 38 ; S ₁ closed
$t_{\mbox{\tiny PHZ}}$; Output HIGH to Tri-state		0.10	2.0	μs	$C_L = 15pF$, Fig. 34 & 38 ; S_2 closed
V.35					
t _{PZL} ; Tri-state to Output LOW		0.10	2.0	μs	C _L = 100pF, Fig. 34 & 38 ; S ₁ closed
t _{PZH} ; Tri-state to Output HIGH		0.10	2.0	μs	$C_L = 100 pF, Fig. 34 & 38; S_2 closed$
t_{PLZ} ; Output LOW to Tri-state		0.10	2.0	μs	$C_L = 15pF$, Fig. 34 & 38 ; S_1 closed
t _{PHZ} ; Output HIGH to Tri-state		0.10	2.0	μs	$C_L = 15pF$, Fig. 34 & 38 ; S_2 closed
TRANSCEIVER TO TRANSCE	IVER SK	EW		()	per Figures 32, 35, 37)
RS-232 Driver		100		ns	$[(t_{PHL})Tx1 - (t_{PHL})Txn]$
		100		ns	$[(t_{PLH})Tx1 - (t_{PLH})Txn]$
RS-232 Receiver		20		ns	$[(t_{PHL})Rx1 - (t_{PHL})Rxn]$
		20		ns	$[(t_{PLH})Rx1 - (t_{PLH})Rxn]$
RS-422 Driver		2		ns	[$(t_{PHL})Tx1 - (t_{PHL})Txn$]
		2		ns	$[(t_{PLH})Tx1 - (t_{PLH})Txn]$
RS-422 Receiver		3		ns	$[(t_{PHL})Rx1 - (t_{PHL})Rxn]$
		3		ns	$[(t_{PLH})Rx1 - (t_{PLH})Rxn]$
RS-423 Driver		5		ns	$[(t_{PHL})Tx2 - (t_{PHL})Txn]$
		5		ns	$[(t_{PLH})Tx2 - (t_{PLH})Txn]$
RS-423 Receiver		5		ns	$[(t_{PHL})Rx2 - (t_{PHL})Rxn]$
		5		ns	$[(t_{PLH})Rx2 - (t_{PLH})Rxn]$
V.35 Driver		4		ns	$[(t_{PHL})Tx1 - (t_{PHL})Txn]$
		4		ns	$[(t_{PLH})Tx1 - (t_{PLH})Txn]$
V.35 Receiver		6		ns	[(t _{PHL})Rx1 – (t _{PHL})Rxn]
		6		ns	$[(t_{PLH})Rx1 - (t_{PLH})Rxn]$



SP3508 Pin Designation					
Pin Number	Pin Name	Description			
1	GND	Signal Ground			
2	SDEN	TxD Driver Enable Input			
3	TTEN	TxCE Driver Enable Input			
4	STEN	ST Driver Enabe Input			
5	RSEN	RTS Driver Enable Input			
6	TREN	DTR Driver Enable Input			
7	RRCEN	DCD Driver Enable Input			
8	RLEN	RL Driver Enable Input			
9	LLEN#	LL Driver Enable Input			
10	RDEN#	RxD Receiver Enabe Input			
11	RTEN#	RxC Receiver Enable Input			
12	TxCEN#	TxC Receiver Enable Input			
13	CSEN#	CTS Receiver Enable Input			
14	DMEN#	DSR Receiver Enable Input			
15	RRTEN#	DCD _{DTE} Receiver Enable Input			
16	ICEN#	RI Receiver Enable Input			
17	TMEN	TM Receiver Enable Input			
18	D0	Mode Select Input			
19	D1	Mode Select Input			
20	D2	Mode Select Input			
21	DLATCH#	Decoder Latch Input			
22	TERM_OFF	Termination Disable Input			
23	VCC	Power Supply Input			
24	C3P	Charge Pump Capacitor			
25	GND	Signal Ground			

SP3508 F	Pin Designation	
Pin Number	Pin Name	Description
26	C3N	Charge Pump Capacitor
27	VSS2	Minus VCC
28	AGND	Signal Ground
29	AVCC	Power Supply Input
30	LOOPBACK#	Loopback Mode Enable Input
31	TxD	TxD Driver TTL Input
32	TxCE	TxCE Driver TTL input
33	ST	ST Driver TTL Input
34	RTS	RTS Driver TTL Input
35	DTR	DTR Driver TTL Input
36	DCD_DCE	DCD _{DCE} Driver TTL Input
37	RL	RL Driver TTL Input
38	LL	LL Driver TTL Input
39	RxD	RxD Receiver TTL Output
40	RxC	RxC Receiver TTL Output
41	TxC	TxC Receiver TTL Output
42	CTS	CTS Receiver TTL Output
43	DSR	DSR Receiver TTL Output
44	DCD_DTE	DCD _{DTE} Receiver TTL Output
45	RI	RI Receiver TTL Output
46	TM	TM Receiver TTL Output
47	GND	Signal Ground
48	VCC	Power Supply Input
49	RD(B)	RxD Non-Inverting Input
50	RD(A)	RxD Inverting Input

SP3508 Pin Designation

Pin Number	Pin Name	Description
51	RT(B)	RxC Non-Inverting Input
52	RT(A)	RxC Inverting Input
53	TxC(B)	TxC Non-Inverting Input
54	GND	Signal Ground
55	TxC(A)	TxC Inverting Input
56	CS(B)	CTS Non-Inverting Input
57	CS(A)	CTS Inverting Input
58	DM(B)	DSR Non-Inverting Input
59	DM(A)	DSR Inverting Input
60	GNDV10	V.10 RX Reference Node
61	RRT(B)	DCD _{DTE} Non-Inverting Input
62	RRT(A)	DCD _{DTE} Inverting Input
63	IC	RI Receiver Input
64	TM(A)	TM Receiver Input
65	LL(A)	LL Driver Output
66	VCC	Power Supply Input
67	RL(A)	RL Driver Output
68	VSS1	-2xVCC Charge Pump Output
69	C2N	Charge Pump Capacitor
70	C1N	Charge Pump Capacitor
71	GND	Signal Ground
72	C2P	Charge Pump Capacitor
73	VCC	Power Supply Input
74	C1P	Charge Pump Capacitor
75	GND	Signal Ground

SP3508 Pin Designation

Pin Number	Pin Name	Description
76	VDD	2xVCC Charge Pump Output
77	RRC(B)	DCD _{DCE} Non-Inverting Output
78	VCC	Power Supply Input
79	RRC(A)	DCD _{DCE} Inverting Output
80	GND	Signal Ground
81	RS(A)	RTS Inverting Output
82	VCC	Power Supply Input
83	RS(B)	RTS Non-Inverting Output
84	GND	Signal Ground
85	TR(A)	DTR Inverting Output
86	VCC	Power Supply Input
87	TR(B)	DTR Non-Inverting Output
88	GND	Signal Ground
89	ST(A)	ST Inverting Output
90	VCC	Power Supply Input
91	ST(B)	ST Non-Inverting Output
92	GND	Signal Ground
93	TT(A)	TxCE Inverting Output
94	VCC	Power Supply Input
95	TT(B)	TxCE Non-Inverting Output
96	GND	Signal Ground
97	SD(A)	TxD Inverting Output
98	VCC	Power Supply Input
99	SD(B)	TxD Non-Inverting Output
100	VCC	Power Supply Input

SP3508 Driver Table

Driver Output Pin	V.35 Mode	EIA-530 Mode	RS-232 Mode (V.28)	EIA-530A Mode	RS-449 Mode (V.36)	X.21 Mode (V.11)	Shutdown	Suggested Signal
MODE (D0, D1, D2)	001	010	011	100	101	110	111	
T ₁ OUT(a)	V.35	V.11	V.28	V.11	V.11	V.11	High-Z	TxD(a)
T ₁ OUT(b)	V.35	V.11	High-Z	V.11	V.11	V.11	High-Z	TxD(b)
T ₂ OUT(a)	V.35	V.11	V.28	V.11	V.11	V.11	High-Z	TxCE(a)
T ₂ OUT(b)	V.35	V.11	High-Z	V.11	V.11	V.11	High-Z	TxCE(b)
T ₃ OUT(a)	V.35	V.11	V.28	V.11	V.11	V.11	High-Z	TxC_DCE(a)
T ₃ OUT(b)	V.35	V.11	High-Z	V.11	V.11	V.11	High-Z	TxC_DCE(b)
T ₄ OUT(a)	V.28	V.11	V.28	V.11	V.11	V.11	High-Z	RTS(a)
T ₄ OUT(b)	High-Z	V.11	High-Z	V.11	V.11	V.11	High-Z	RTS(b)
T₅OUT(a)	V.28	V.11	V.28	V.10	V.11	V.11	High-Z	DTR(a)
T₅OUT(b)	High-Z	V.11	High-Z	High-Z	V.11	V.11	High-Z	DTR(b)
T ₆ OUT(a)	V.28	V.11	V.28	V.11	V.11	V.11	High-Z	DCD_DCE(a)
T ₆ OUT(b)	High-Z	V.11	High-Z	V.11	V.11	V.11	High-Z	DCD_DCE(b)
T ₇ OUT(a)	V.28	V.10	V.28	V.10	V.10	High-Z	High-Z	RL
T ₈ OUT(a)	V.28	V.10	V.28	V.10	V.10	High-Z	High-Z	LL

Table 1. Driver Mode Selection

SP3508 Receiver Table

Receiver Input Pin	V.35 Mode	EIA-530 Mode	RS-232 Mode (V.28)	EIA-530A Mode	RS-449 Mode (V.36)	X.21 Mode (V.11)	Shutdown	Suggested Signal
MODE (D0, D1, D2)	001	010	011	100	101	110	111	
R ₁ IN(a)	V.35	V.11	V.28	V.11	V.11	V.11	High-Z	RxD(a)
R ₁ IN(b)	V.35	V.11	High-Z	V.11	V.11	V.11	High-Z	RxD(b)
R ₂ IN(a)	V.35	V.11	V.28	V.11	V.11	V.11	High-Z	RxC(a)
R ₂ IN(b)	V.35	V.11	High-Z	V.11	V.11	V.11	High-Z	RxC(b)
R ₃ IN(a)	V.35	V.11	V.28	V.11	V.11	V.11	High-Z	TxC_DTE(a)
R ₃ IN(b)	V.35	V.11	High-Z	V.11	V.11	V.11	High-Z	TxC_DTE(b)
R ₄ IN(a)	V.28	V.11	V.28	V.11	V.11	V.11	High-Z	CTS(a)
R ₄ IN(b)	High-Z	V.11	High-Z	V.11	V.11	V.11	High-Z	CTS(b)
R _s IN(a)	V.28	V.11	V.28	V.10	V.11	V.11	High-Z	DSR(a)
R _s IN(b)	High-Z	V.11	High-Z	High-Z	V.11	V.11	High-Z	DSR(b)
R ₆ IN(a)	V.28	V.11	V.28	V.11	V.11	V.11	High-Z	DCD_DTE(a)
R ₆ IN(b)	High-Z	V.11	High-Z	V.11	V.11	V.11	High-Z	DCD_DTE(b)
R ₇ IN(a)	V.28	V.10	V.28	V.10	V.10	High-Z	High-Z	RI
R ₈ IN(a)	V.28	V.10	V.28	V.10	V.10	High-Z	High-Z	TM

Table 2. Receiver Mode Selection

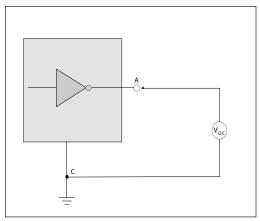


Figure 1. V.28 Driver Output Open Circuit Voltage

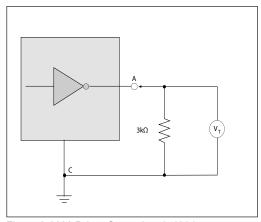


Figure 2. V.28 Driver Output Loaded Voltage

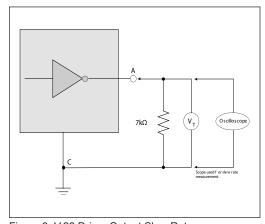


Figure 3. V.28 Driver Output Slew Rate

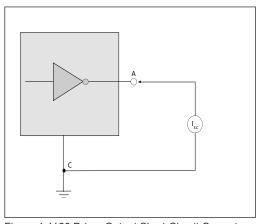


Figure 4. V.28 Driver Output Short-Circuit Current

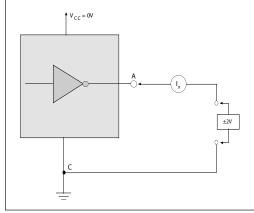


Figure 5. V.28 Driver Output Power-Off Impedance

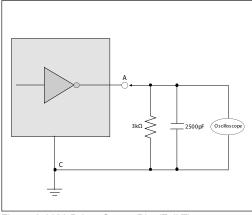


Figure 6. V.28 Driver Output Rise/Fall Times

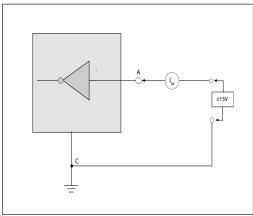


Figure 7. V.28 Receiver Input Impedance

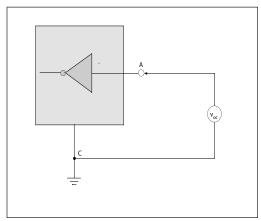


Figure 8. V.28 Receiver Input Open Circuit Bias

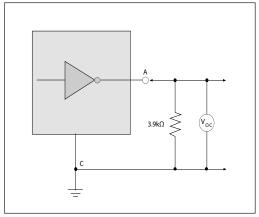


Figure 9. V.10 Driver Output Open-Circuit Voltage

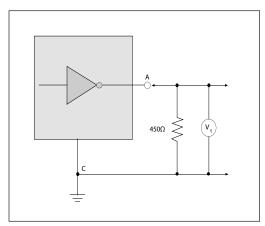


Figure 10. V.10 Driver Output Test Terminated Voltage

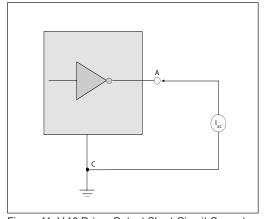


Figure 11. V.10 Driver Output Short-Circuit Current

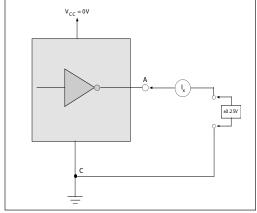


Figure 12. V.10 Driver Output Power-Off Current

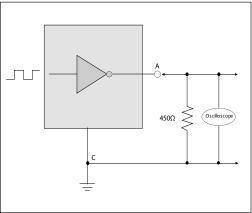


Figure 13. V.10 Driver Output Transition Time

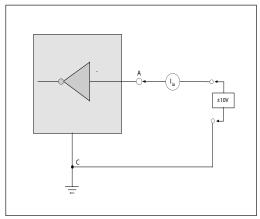


Figure 14. V.10 Receiver Input Current

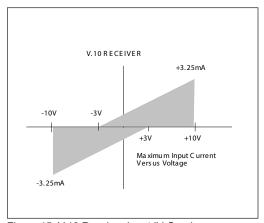


Figure 15. V.10 Receiver Input IV Graph

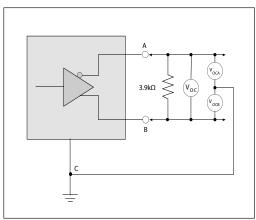


Figure 16. V.11 Driver Output Open-Circuit Voltage

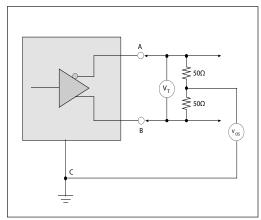


Figure 17. V.11 Driver Output Test Terminated Voltage

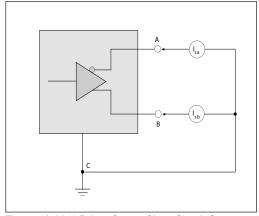


Figure 18. V.11 Driver Output Short-Circuit Current

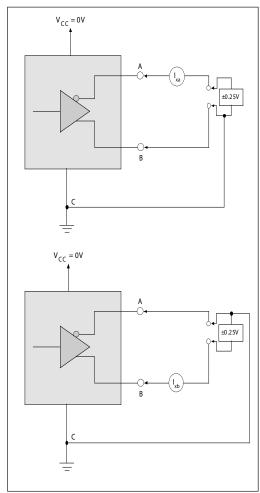


Figure 19. V.11 Driver Output Power-Off Current

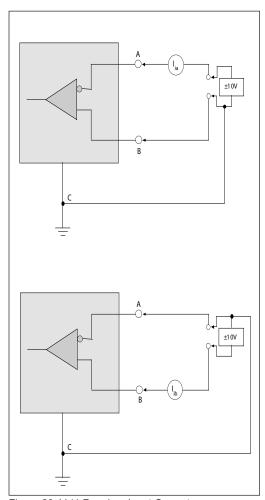


Figure 20. V.11 Receiver Input Current

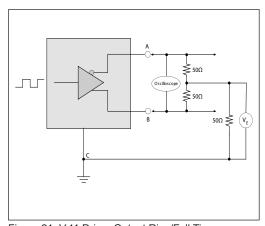


Figure 21. V.11 Driver Output Rise/Fall Time

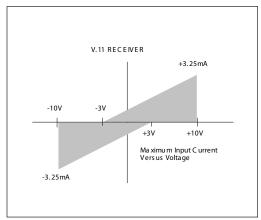


Figure 22. V.11 Receiver Input IV Graph

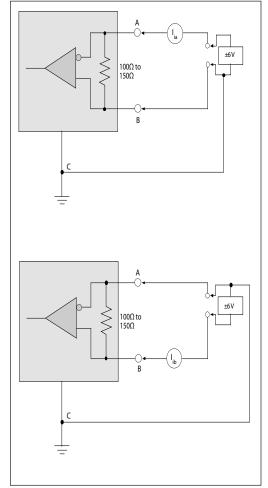


Figure 23. V.11 Receiver Input Current w/ Termina-

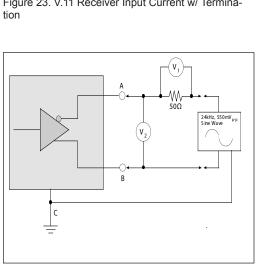


Figure 26. V.35 Driver Output Source Impedance

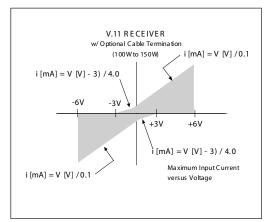


Figure 24. V.11 Receiver Input Graph with Termination

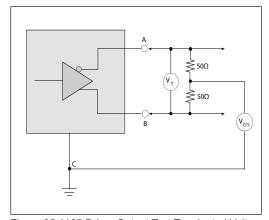


Figure 25. V.35 Driver Output Test Terminated Voltage

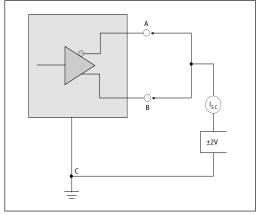


Figure 27. V.35 Driver Output Short-Circuit Impedance

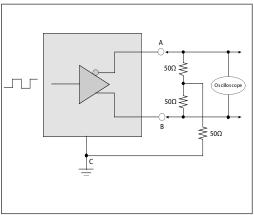


Figure 28. V.35 Driver Output Rise/Fall Time

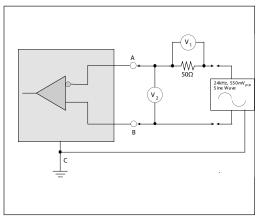


Figure 29. V.35 Receiver Input Source Impedance

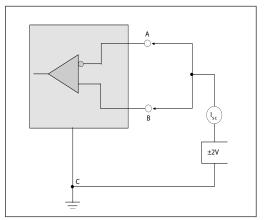


Figure 30. V.35 Receiver Input Short-Circuit Impedance

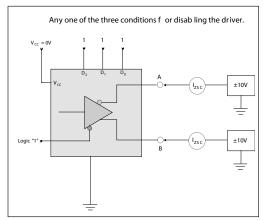


Figure 31. Driver Output Leakage Current Test

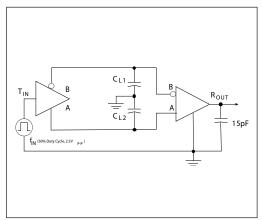


Figure 32. Driver/Receiver Timing Test Circuit

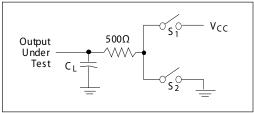


Figure 33. Driver Timing Test Load Circuit

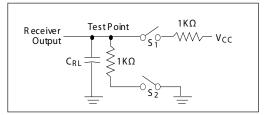


Figure 34. Receiver Timing Test Load Circuit

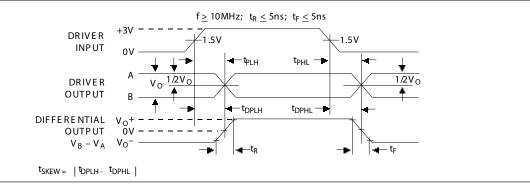


Figure 35. Driver Propagation Delays

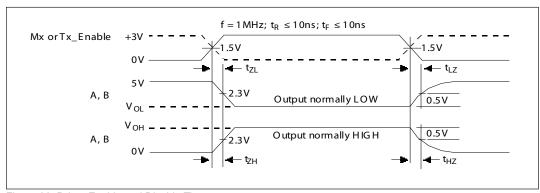


Figure 36. Driver Enable and Disable Times

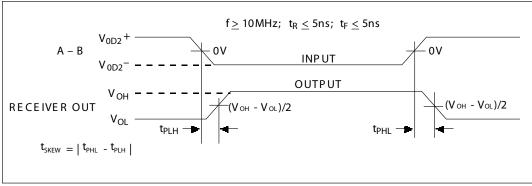


Figure 37. Receiver Propagation Delays

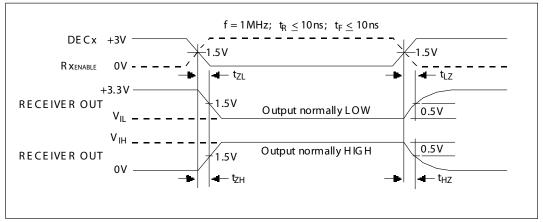


Figure 38. Receiver Enable and Disable Times

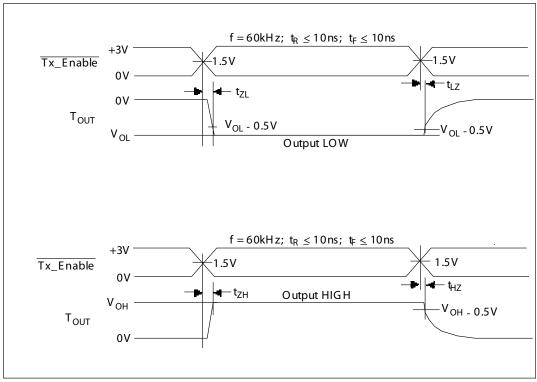


Figure 39. V.28 (RS-232) and V.10 (RS-423) Driver Enable and Disable Times

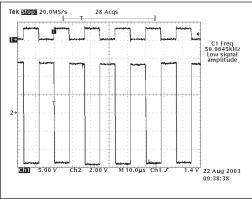


Figure 40. Typical V.10 Driver Output Waveform.

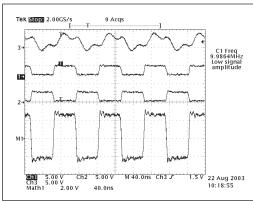


Figure 41. Typical V.11 Driver Output Waveform.

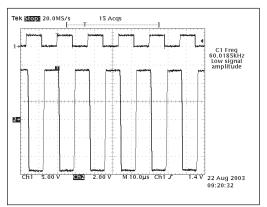


Figure 42. Typical V.28 Driver Output Waveform.

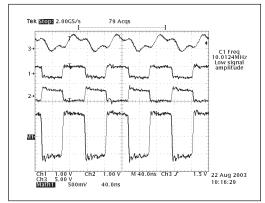


Figure 43. Typical V.35 Driver Output Waveform.

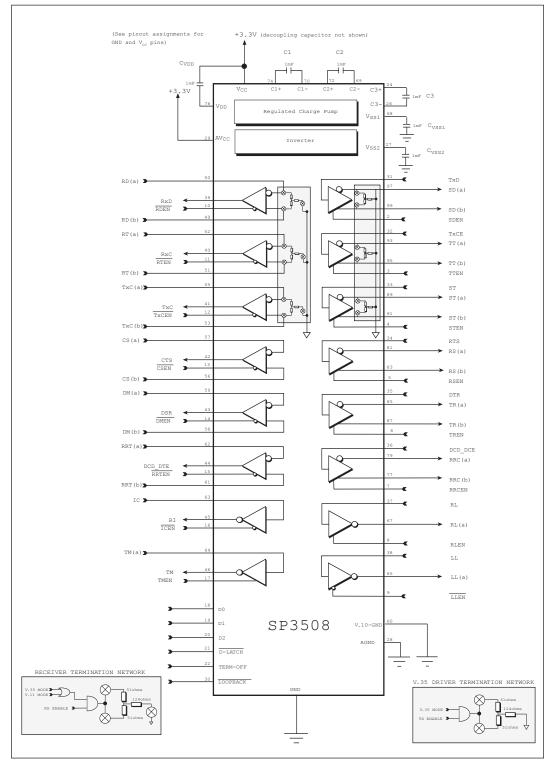


Figure 44. Functional Diagram

The SP3508 contains highly integrated serial transceivers that offer programmability between interface modes through software control. The SP3508 offers the hardware interface modes for RS-232 (V.28), RS-449/V.36 (V.11 and V.10), EIA-530 (V.11 and V.10), EIA-530A (V.11 and V.10), V.35 (V.35 and V.28) and X.21(V.11). The interface mode selection is done via three control pins, which can be latched via microprocessor control.

The SP3508 has eight drivers, eight receivers, and a patented on-board charge pump (5,306,954) that is ideally suited for wide area network connectivity and other multiprotocol applications. Other features include digital and line loopback modes, individual enable/disable control lines for each driver and receiver, fail-safe when inputs are either open or shorted.

THEORY OF OPERATION

The SP3508 device is made up of

- 1) the drivers
- the receivers
- 3) charge pumps
- 4) DTE/DCE switching algorithm
- 5) control logic.

Drivers

The SP3508 has eight enhanced independent drivers. Control for the mode selection is done via a three-bit control word into D0, D1, and D2. The drivers are prearranged such that for each mode of operation, the relative position and functionality of the drivers are set up to accommodate the selected interface mode. As the mode of the drivers is changed, the electrical characteristics will change to support the required signal levels. The mode of each driver in the different interface modes that can be selected is shown in Table 1.

There are four basic types of driver circuits – ITU-T-V.28 (RS-232), ITU-T-V.10 (RS-423), ITU-T-V.11 (RS-422), and CCITT-V.35.

The V.28 (RS-232) drivers output single-ended signals with a minimum of $\pm 5V$ (with $3k\Omega\&2500$ pF loading), and can operate over 120kbps. Since the SP3508 uses a charge pump to generate the RS-232 output rails, the driver outputs will never exceed $\pm 10V$. The V.28 driver architecture is similar to Sipex's standard line of RS-232 transceivers.

The RS-423 (V.10) drivers are also single-ended signals which produce open circuit $V_{\rm OL}$ and $V_{\rm OH}$ measurements of $\pm 4.0 \rm V$ to $\pm 6.0 \rm V$. When terminated with a 450Ω load to ground, the driver output will not deviate more than 10% of the open circuit value. This is in compliance of the ITU V.10 specification. The V.10 (RS-423) drivers are used in RS-449/V.36, EIA-530, and EIA-530A modes as Category II signals from each of their corresponding specifications. The V.10 driver can transmit over 120Kbps if necessary.

The third type of drivers are V.11 (RS-422) differential drivers. Due to the nature of differential signaling, the drivers are more immune to noise as opposed to single-ended transmission methods. The advantage is evident over high speeds and long transmission lines. The strength of the driver outputs can produce differential signals that can maintain +2V differential output levels with a load of 100Ω . The strength allows the SP3508 differential driver to drive over long cable lengths with minimal signal degradation. The V.11 drivers are used in RS-449, EIA-530. EIA-530A and V.36 modes as Category I signals which are used for clock and data. Exar's new driver design over its predecessors allow the SP3508 to operate over 20Mbps for differential transmission.

The fourth type of drivers are V.35 differential drivers. There are only three available on the SP3508 for data and clock (TxD, TxCE, and TxC in DCE mode).

These drivers are current sources that drive loop current through a differential pair resulting in a 550mV differential voltage at the receiver. These drivers also incorporate fixed termination networks for each driver in order to set the V_{OH} and V_{OL} depending on load conditions. This termination network is basically a "Y" configuration consisting of two 51 Ω resistors connected in series and a 124 Ω resistor connected between the two 50 Ω resistors to GND. Filtering can be done on these pins to reduce common mode noise transmitted over the transmission line by connecting a capacitor to ground.

The drivers also have separate enable pins which simplifies half-duplex configurations for some applications, especially programmable DTE/DCE. The enable pins will either enable or disable the output of the drivers according to the appropriate active logic illustrated on Figure 44. The enable pins have internal pull-up and pull-down devices, depending on the active polarity of the receiver, that enable the driver upon power-on if the enable lines are left floating. During disabled conditions, the driver outputs will be at a high impedance 3-state.

The driver inputs are both TTL or CMOS compatible. All driver inputs have an internal pull-up resistor so that the output will be at a defined state at logic LOW ("0"). Unused driver inputs can be left floating. The internal pull-up resistor value is approximately $500k\Omega$.

Receivers

The SP3508 has eight enhanced independent receivers. Control for the mode selection is done via a three-bit control word that is the same as the driver control word. Therefore, the modes for the drivers and receivers are identical in the application. Like the drivers, the receivers are prearranged for the specific requirements of the synchronous serial interface. As the operating mode of the receivers is changed, the electrical characteristics will change to support the required serial interface protocols of the receivers. Table 1 shows the mode of each receiver in the different

interface modes that can be selected. There are two basic types of receiver circuits—ITU-T-V.28 (RS-232) and ITU-T-V.11, (RS-422).

The RS-232 (V.28) receiver is single-ended and accepts RS-232 signals from the RS-232 driver. The RS-232 receiver has an operating input voltage range of +15V and can receive signals downs to +3V. The input sensitivity complies with RS-232 and V.28 at +3V. The input impedance is $3k\Omega$ to $7k\Omega$ in accordance to RS-232 and V.28. The receiver output produces a TTL/CMOS signal with a +2.4V minimum for a logic "1" and a +0.4V maximum for a logic "0". The RS-232 (V.28) protocol uses these receivers for all data, clock and control signals. They are also used in V.35 mode for control line signals: CTS, DSR, LL, and RL. The RS-232 receivers can operate over 120kbps.

The second type of receiver is a differential type that can be configured internally to support ITU-T-V.10 and CCITT-V.35 depending on its input conditions. This receiver has a typical input impedance of $10k\Omega$ and a differential threshold of less than ± 200 mV, which complies with the ITU-T-V.11 (RS-422) specifications. V.11 receivers are used in RS-449/V.36, EIA-530, EIA-530A and X.21 as Category I signals for receiving clock, data, and some control line signals not covered by Category II V.10 circuits. The differential V.11 transceiver has improved architecture that allows over 20Mbps transmission rates.

Receivers dedicated for data and clock (RxD, RxC, TxC) incorporate internal termination for V.11. The termination resistor is typically 120 Ω connected between the A and B inputs. The termination is essential for minimizing crosstalk and signal reflection over the transmission line . The minimum value is guaranteed to exceed $100\Omega,$ thus complying with the V.11 and RS-422 specifications. This resistor is invoked when the receiver is operating as a V.11 receiver, in modes EIA-530, EIA-530A, RS-449/V.36, and X.21.

The same receivers also incorporate a termination network internally for V.35 applications. For V.35, the receiver input termination is a "Y" termination consisting of two 51Ω resistors connected in series and a 124Ω resistor connected between the two 50Ω resistors and GND. The receiver itself is identical to the V.11 receiver.

The differential receivers can be configured to be ITU-T-V.10 single-ended receivers by internally connecting the non-inverting input to ground. This is internally done by default from the decoder. The non-inverting input is rerouted to V10GND and can be grounded separately. The ITU-T-V.10 receivers can operate over 120Kbps and are used in RS-449/V.36, E1A-530, E1A-530A and X.21 modes as Category II signals as indicated by their corresponding specifications. All receivers include an enable/disable line for disabling the receiver output allowing convenient half-duplex configurations. The enable pins will either enable or disable the output of the receivers according to the appropriate active logic illustrated on Figure 44. The receiver's enable lines include an internal pull-up or pull-down device, depending on the active polarity of the receiver, that enables the receiver upon power up if the enable lines are left floating. During disabled conditions, the receiver outputs will be at a high impedance state. If the receiver is disabled any associated termination is also disconnected from the inputs.

All receivers include a fail-safe feature that outputs a logic high when the receiver inputs

are open, terminated but open, or shorted together. For single-ended V.28 and V.10 receivers, there are internal $5k\Omega$ pull-down resistors on the inputs which produces a logic high ("1") at the receiver outputs. The differential receivers have a proprietary circuit that detect open or shorted inputs and if so, will produce a logic HIGH ("1") at the receiver output.

CHARGE PUMP

SP3508 uses an internal capacitive charge pump to generate Vdd and Vss. The design is a patented (5,306,954) four-phased voltage shifting charge pump converters that converts the input voltage of 3.3V to nominal output voltages of +/-6V (Vdd & Vss1). SP3508 also includes an inverter block that inverts Vcc to -Vcc (Vss2). There is a free-running oscillator that controls the four phases of the voltage shifting. A description of each phase follows.

4-phased doubler pump

Phase 1

- $V_{\rm SS1}$ charge storage -During this phase of the clock cycle, the positive side of capacitors C1 and C2 are initially charged to $V_{\rm CC}$. C1+ is then switched to ground and the charge in C1- is transferred to C2-. Since C2+ is connected to $V_{\rm CC}$, the voltage potential across capacitor C2 is now 2x $V_{\rm CC}$.

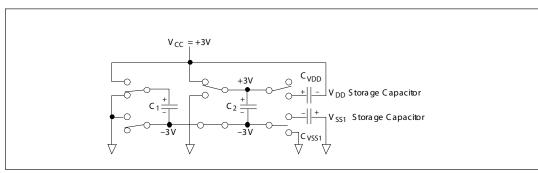


Figure 45. Charge Pump - Phase 1.

Phase 2

- $V_{\rm SS1}$ transfer -Phase two of the clock connects the negative terminal of C2 to the $V_{\rm SS1}$ storage capacitor and the positive terminal of C2 to ground, and transfers the negative generated voltage to $C_{\rm VSS1}$. This generated voltage is regulated to -5.5V. Simultaneously, the positive side of the capacitor C1 is switched to $V_{\rm CC}$ and the negative side is connected to ground.

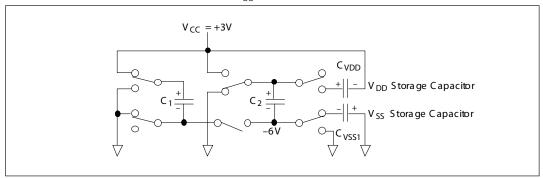


Figure 46. Charge Pump - Phase 2.

Phase 3

 $-V_{DD}$ charge storage -The third phase of the clock is identical to the first phase-the charge transferred in C1 produces - V_{CC} in the negative terminal of C1 which is applied to the negative side of the capacitor C2. Since C2+ is at V_{CC} , the voltage potential across C2 is $2xV_{CC}$.

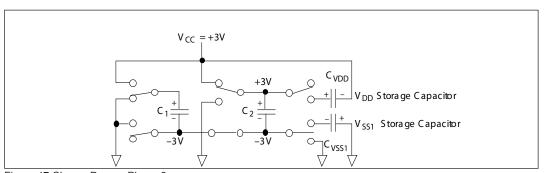


Figure 47. Charge Pump - Phase 3.

Phase 4

- V_{DD} transfer -The fourth phase of the clock connects the negative terminal of C2 to ground, and transfers the generated 5.5V across C2 to C_{VDD} , the V_{DD} storage capacitor. This voltage is regulated to +5.5V. At the regulated voltage, the internal oscillator is disabled and simultaneously with this, the positive side of capacitor C1 is switched to V_{CC} and the negative side is connected to ground, and the cycle begins again. The charge pump cycle will continue as long as the operational conditions for the internal oscillator are present. Since both V+ and V- are separately generated from V_{CC} ; in a no-load condition V+ and V- will be symmetrical. Older charge pump approaches that generate V- from V+ will show a decrease in the magnitude of V- compared to V+ due to the inherent inefficiencies in the design. The clock rate for the charge pump typically operates at 250kHz. The external capacitors can be as low as $1\mu F$ with a 16V breakdown voltage rating.

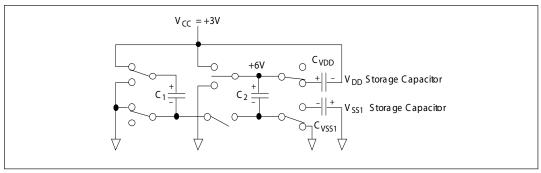


Figure 48. Charge Pump - Phase 4.

2-phased inverter pump

Phase 1

Please refer to figure below: In the first phase of the clock cycle, switches S2 and S4 are opened and S1 and S3 closed. This connects the flying capacitor, C3, from Vin to ground. C3 charge up to the input voltage applied at Vcc.

Phase 2

In the second phase of the clock cycle, switches S2 and S4 are closed and S1 and S3 are opened. This connects the flying capacitor, C3, in parallel with the output capacitor, C_{VSS2} . The Charge stored in C3 is now transferred to C_{VSS2} . Simultaneously, the negative side of C_{VSS2} is connected to V_{SS2} and the positive side is connected to ground. With the voltage across C_{VSS2} smaller than the voltage across C3, the charge flows from C3 to C_{VSS2} until the voltage at the V_{SS2} equals - V_{CC} .

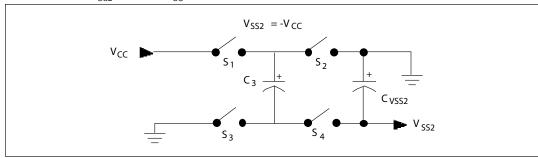


Figure 49. Circuit for an Ideal Voltage Inverter.

Spare dr Quality,	17	46	16	45	15	4	14	43	13	42	12	41	11	40	10	39	9	38	8	37	7	36	6	35	5	34	4	33	ω	32	2	31	Pin Number	Interfac	
Spare drivers and receivers may be used for optional signals (Signal Ouality. Rate Detect, Standby) or may be disabled using individual	TMEN	TM	ICEN#	R	RRTEN#	DCD_DTE	DMEN#	DSR	CSEN#	CTS	TxCEN#	TxC	RTEN#	RxC	RDEN#	RxD	LLEN#	רר	RLEN	₽	RRCEN	DCD_DCE	TREN	DTR	RSEN	RTS	STEN	TS	TIEN	TxCE	SDEN	_	Pin Mnemonic	Interface to System Logic	SP3508 Mult
nay be used for opi		Receiver_8		Receiver_7		Receiver_6		Receiver_5		Receiver_4		Receiver_3		Receiver_2		Receiver_1		Driver_8		Driver_7		Driver_6		Driver_5		Driver_4		Driver 3		Driver 2		Driver 1	Circuit		SP3508 Multiprotocol Configured as DCE
tional signals (Sig		TM(A)		С	RRT(B)	RRT(A)	DM(B)	DM(A)	CS(B)	CS(A)	TxC(B)	TxC(A)	RT(B)	RT(A)	RD(B)	RD(A)		LL(A)		RL(A)	RRC(B)	RRC(A)	TR(B)	TR(A)	RS(B)	RS(A)	ST(B)	ST(A)	∏(B)	П(A)	SD(B)	SD(A)	Pin Mnemonic	Interface to Port- Connector	d as DCE
nal		64		63	61	62	58	59	56	57	53	55	51	52	49	50		65		67	77	79	87	85	83	81	91	89	95	93	99	\dashv	Pin	o Port- ctor	
Pin as		V.28		V.28				V.28		V.28				V.28		V.28		V.28		V.28		V.28		V.28		V.28		V.28		V.28		V.28	Signal Type	R	Recon
signmen		L		RL				CD	_	CA			_	DA		BA		MT		æ		CF		2	+	æ	+	DB	+	DD	+	+	Mnemo	RS-232 or V.24	nmendec
ts and sig		18		21				20		4				24		2		25		22		8		6		5		15		17		4	10 DB-25 Pin(F)	V.24	Signals
Pin assignments and signal functions are sub		V.10		V.10			V.11	V.11	V.11	V.11			V.11	V.11	V.11	V.11		V.10			V.11	V.11	V.11	V.11	V.11	V.11	V.11	V.11	V.11	V.11	V.11	-	Signal Type		and Port
Pin assignments and signal functions are subject to national or regional variation and		LL		RL			CD(B)	CD(A)	CA(B)	CA(A)			DA(B)	DA(A)	BA(B)	BA(A)		MT			CF(B)	CF(A)	CC(B)	CC(A)	CB(B)	CB(A)	DB(B)	DB(A)	DD(B)	DD(A)	BB(B)	В.	Mnemo	EIA-530	Recommended Signals and Port Pin Assignments
ubject to		18		21			23			4) 11) 24	12	2		25							+	1	1	1	1		\dashv	4	o DB-25 Pin(F)	0	nments
national		V.10		V.10			V.11	V.11	V.11	V.11			V.11	V.11	V.11	V.11		V.10			V.11	V.11	V.11	V.11	V.11	V.11	V.11	V.11	V.11	V.11	V.11	\dashv	Signal		
or regiona		F		몬			TR(B)	TR(A)	RS(B)	RS(A)			TT(B)	TT(A)	SD(B)	SD(A)		MT			RR(B)	RR(A)	DM(B)	DM(A)	CS(B)	CS(A)	ST(B)	ST(A)	RT(B)	RT(A)	RD(B)	'n	Mnemo nic	RS-449	
l variatio		10		14			30	12	25	7			35	17	22	4		18			31	13	29	=	27	9	23	UT	26	œ !	24	6	o DB-37 Pin(F)		
n and		V.28		V.28				V.28		V.28			V.35	V.35	V.35	V.35		V.28		V.28		V.28		V.28		V.28	V.35	V.35	V.35	V.35	V.35	+	Signal Type		
		141		140				108		105			113	113	103	103		142		125		109		107		106	114	114	115	115	104	104	Mnemo	V.35	
		L		z				I		0			W	C	S	P		NN		_		F		т		D	AA	~	×	<	7	R .	Pin(F)		
** X.21									V.11	٧.11			V.11	V.11	V.11	V.11									V.11	V.11	V.11	V.11	V.11	V.11	V.11	<.11	Signal Type		
** X.21 use either B() or									C(B)	C(A)			X(B)	X(A)	T(B)	T(A)									(B)	Ī(Ā)	S(B)	S(A)	B(B)	B(A)	R(B)		Mnemo	X.21	
B() or									10	3			14**	7**	9	2									12	5	13	6	14**	7**	=	4	DB-15 Pin(F)		

DTE CONFIGURATION

SP3508 Multip	SP3508 Multiprotocol Configured as DTE	d as DTE		Recomr	nended S	ignals an	d Port Pi	Recommended Signals and Port Pin Assignments	ents									
Interface to System Logic		Interface to Port- Connector	Port- tor	RS	RS-232 or V.24	24		EIA-530			RS-449			V.35			X.21	
Pin			Pin	Signal	Mnemo	DB-25	Signal	Mnemo		Signal	Mnemo	DB-37	Signal	ō			Mnemo	DB-15
Number Pin Mnemonic	Circuit	Pin Mnemonic	Number	Type	nic	Pin(M)	Type	nic	Pin(M)	Type	nic	Pin(M)	_	-	Pin(M)	Type	nic	Pin(M)
31 TxD	Driver_1	SD(A)	97	V.28	BA	2	V.11	BA(A)	2	V.11	SD(A)	4	V.35	103	P	V.11	T(A)	2
2 SDEN		SD(B)	99				V.11	BA(B)	12	V.11	SD(B)	22	V.35	103	S	V.11	T(B)	9
32 TxCE	Driver_2	П(А)	93	V.28	DA	24	V.11	DA(A)	24	V.11	TT(A)	17	V.35	113	_	V.11	X(A)	7**
		П(B)	95				V.11	DA(B)	11	V.11	TT(B)	35	V.35	113	×	V.11	X(B)	14**
33 ST	Driver_3	ST(A)	89															
4 STEN		ST(B)	91															
34 RTS	Driver_4	RS(A)	81	V.28	S	4	V.11	CA(A)	4	V.11	RS(A)	7	V.28	105	^	V.11	C(A)	ω
5 RSEN		RS(B)	83				V.11	CA(B)	19	V.11	RS(B)	25				V.11	C(B)	10
35 DTR	Driver_5	TR(A)	85	V.28	G	20	V.11	CD(A)	20	V.11	TR(A)	12	V.28	108	I			
6 TREN		TR(B)	87				V.11	CD(B)	23	V.11	TR(B)	30						
36 DCD_DCE	Driver_6	RRC(A)	79															
7 RRCEN		RRC(B)	77															
37 RL	Driver_7	RL(A)	67	V.28	P	21	V.10	P	21	V.10	몬	14	V.28	140	z			
8 RLEN																		
38 LL	Driver_8	LL(A)	65	V.28	F	18	V.10	F	18	V.10	F	10	V.28	141	_			
9 LLEN#																		
39 RxD	Receiver_1	RD(A)	50	V.28	BB	ω	V.11	BB(A)	ω	V.11	RD(A)	6	V.35	104	R	V.11	R(A)	4
10 RDEN#		RD(B)	49				V.11	BB(B)	16	V.11	RD(B)	24	V.35	104	-1	V.11	R(B)	=1
40 RxC	Receiver_2	RT(A)	52	V.28	DD	17	V.11	DD(A)	17	V.11	RT(A)	8	V.35	115	<	V.11	B(A)	7**
11 RTEN#		RT(B)	51				V.11	DD(B)	9	V.11	RT(B)	26	V.35	115	×	V.11	B(B)	14**
41 TxC	Receiver_3	TxC(A)	55	V.28	DB	15	V.11	DB(A)	15	V.11	ST(A)	5	V.35	114	~	V.11	S(A)	6
12 TxCEN#		TxC(B)	53				V.11	DB(B)	12	V.11	ST(B)	23	V.35	114	AA	V.11	S(B)	13
42 CTS	Receiver_4	CS(A)	57	V.28	æ	5	V.11	CB(A)	5	V.11	CS(A)	9	V.28	106	D	V.11	(A)	5
13 CSEN#		CS(B)	56				V.11	CB(B)	13	V.11	CS(B)	27				V.11	I(B)	12
43 DSR	Receiver_5	DM(A)	59	V.28	2	6	V.11	CC(A)	6	V.11	DM(A)	11	V.28	107	т			
14 DMEN#		DM(B)	58				V.11	CC(B)	22	V.11	DM(B)	29						
44 DCD_DTE	Receiver_6	RRT(A)	62	V.28	유	8	V.11	CF(A)	8	V.11	RR(A)	13	V.28	109	T			
15 RRTEN#		RRT(B)	61				V.11	CF(B)	10	V.11	RR(B)	31						
45 RI	Receiver_7	r	63	V.28	Э	22							V.28	125	_			
16 ICEN#																		
46 TM	Receiver_8	TM(A)	64	V.28	MT	25	V.10	TM	25	V.10	TM	18	V.28	142	Z			
17 TMEN																		
Spare drivers and receivers may be used for optional signals (Signal Quality, Rate Detect, Standby) or may be disabled using individual enable pins for each driver and receiver	ay be used for opt) or may be disable ld receiver	ional signals (Sign ed using individua	= a	Pin assi propriet	gnments tary / non	and signa	al functio	Pin assignments and signal functions are sub proprietary / non-standard implementations	oject to n	ational or	Pin assignments and signal functions are subject to national or regional variation and proprietary / non-standard implementations	variation	and			** X.21 use either B() or X(), not both	e either B oth	() or
							١		١									

TERM OFF FUNCTION

The SP3508 contains a TERM_OFF pin that disables all three receiver input termination networks regardless of mode. This allows the device to be used in monitor mode applications typically found in networking test equipment.

The TERM_OFF pin internally contains a pull-down device with an impedance of over $500k\Omega$, which will default in a "ON" condition during power-up if V.35 receivers enable line and the SHUTDOWN mode from the decoder will disable the termination regardless of TERM OFF.

LOOPBACK FUNCTION

The SP3508 contains a LOOPBACK pin that invokes a loopback path. This loopback path is illustrated in Figure 50. LOOPBACK has an internal pull-up resistor that defaults to normal mode during power up or if the pin is left floating. During loopback, the driver output and receiver input characteristics will still adhere to its appropriate specifications.

DECODER AND D LATCH FUNCTION

The SP3508 contains a D_LATCH pin that latches the data into the D0, D1 and D2 decoder inputs. If tied to a logic LOW ("0"), the latch is transparent, allowing the data at the decoder inputs to propagate through and program the SP3508 accordingly. If tied to a logic HIGH ("1"), the latch locks out the data and prevents the mode from changing until this pin is brought to a logic LOW.

There are internal pull-up devices on D0, D1 and D2, which allow the device to be in SHUTDOWN mode ("111") upon power up. However, if the device is powered-up with the D_LATCH at a logic HIGH, the decoder state of the SP3508 will be undefined.

CTR1/CTR2 EUROPEAN COMPLIANCY

As with all of Exar's previous multi-protocol serial transceiver IC's the drivers and receivers have been designed to meet all the requirements to NET1/NET2 and TBR2 in order to meet CTR1/CTR2 compliancy. The SP3508 is also tested in-house at Exar and adheres to all the NET1/2 physical layer testing and the ITU Series V specifications before shipment. Please note that although the SP3508, as with its predecessors, adhere to CRT1/CTR2 compliancy testing, any complex or usual configuration should be double-checked to ensure CTR1/CTR2 compliance. Consult the factory for details.

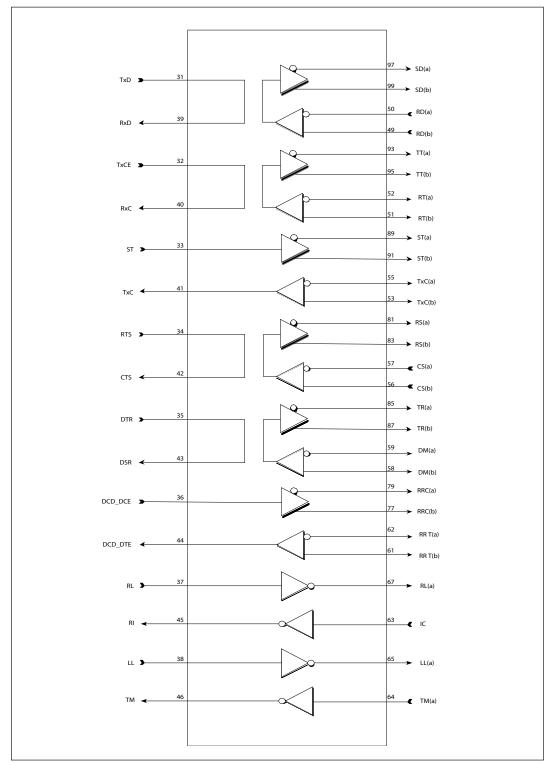


Figure 50. Loopback Path

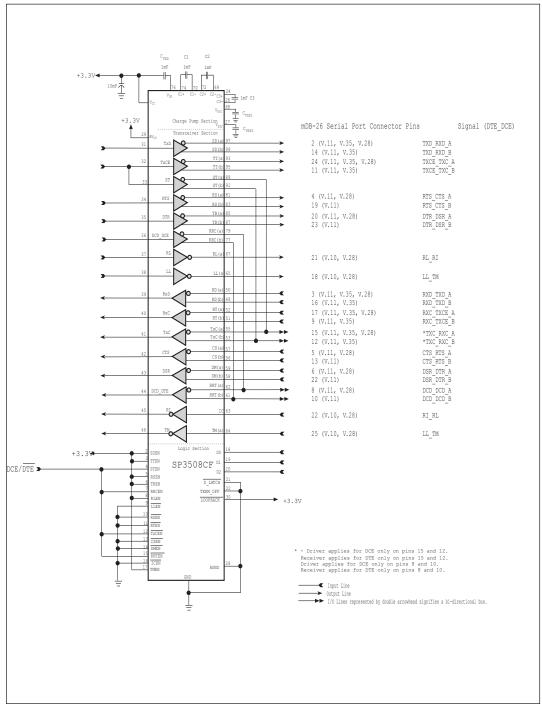
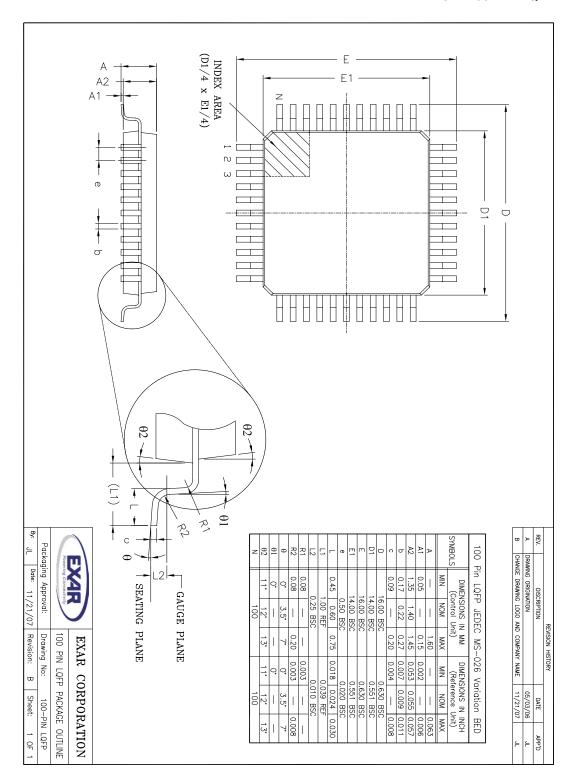


Figure 51. SP3508 Typical Operating Configuration to Serial Port Connector with DCE/DTE programmability



Part Number	Temperature Range	Package Types
SP3508CF-L		100-pin JEDEC LQFP
SP3508EF-L	40°C to +85°C	100-pin JEDEC LQFP

REVISION HISTORY

Date	Revision	Description
1/12/04	А	Implemented Tracking revision
2/27/04	В	Included Diamond column in spec table inidcating which specs apply over full operating temperature range. Correct typo to Fig. 51 pin 61 and 62.
3/31/04	С	Corrected max dimension for symbol c on LQFP package outline
6/03/04	D	Added table to page 27 and 28
10/12/04	E	Certified conformance to NET1/NET2 and TBR-1/TBR-2 TUV by TUV Rheinland (Test report # TBR2/30451940.001/04)
10/29/04	F	Corrected V.28 Driver Open circuit values, pages 27 and 28 both for DCE and DTE that BA(B) should connect to pin 14.
7/17/08	1.0.0	Change Revision format from letter code to number code. Change Logo, footnote and notice statement from Sipex to Exar. Add T _J limits to Absolute Maximum Ratings. Change propagation delay limit specification for V.11 and V.35 Driver/Receiver from 60ns Maximum to 85ns Maximum. Update ordering information to show only RoHS packaging (-L) is available.

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